



Solder plus Support

# Epoxy 4044



## Surface Mount Epoxy

### Features:

- Recommended For Printing Applications
- Good for High Speed Placement Equipment
- Fast Curing
- One Part Epoxy
- Non-Stringing Formula
- High Shear Strength

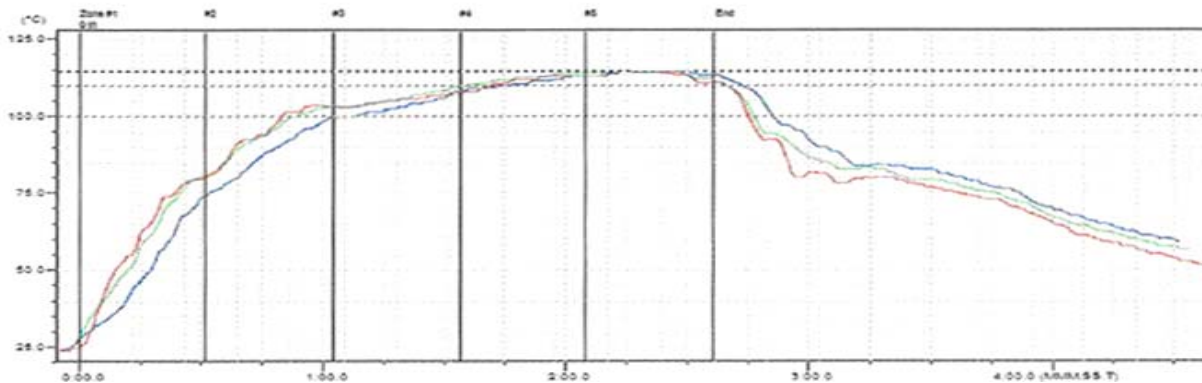
### Description:

Epoxy 4044 is a single component, epoxy adhesive used for bonding SMT components to a PWB for double sided reflow or wave solder assembly. Epoxy 4044 has a formulated tolerance to shear-thinning which is suitable for automated printing equipment and quick cure properties when exposed to heat. Viscosity and surface tension of Epoxy 4044 are adequate for use with high speed placement equipment.

### Application:

- Epoxy 4044 is delivered ready to use, and is available in syringes, cartridges, and jars.
- Epoxy 4044 is formulated for printing applications using a clean screen or stencil and the epoxy is deposited to the circuit board in the same manner as solder paste. Machine parameters and screen/stencil design should be optimized accordingly.
- Stencil aperture design will impact the Epoxy 4044 deposit shape and height and will need to be adjusted for various component types.
- Bond strength will vary depending on component type, adhesive deposit size, cure and type of solder mask or photo resist.

### Reflow Profile:



Time from Ambient to 75°C	Time from 75°C to 100°C	Time from 100°C to Peak: 120°C ± 5°C	Maximum Time at 120°C ± 5°C	Maximum Time Ambient to Peak
30 seconds ± 10	30 seconds ± 10	60 seconds ± 10	60 seconds	< 3 minutes

### Cleaning:

Uncured adhesive may be removed from the PCB with IPA. Cured epoxy or removal of components bonded with Epoxy 4044 may be facilitated with the addition of heat from a heat gun or a hot air jet. A temperature of approximately 120°C should be adequate.

**Handling and Storage:**

- This material has a shelf life of 6 months when stored in refrigeration.
- Clean dispensing nozzles thoroughly after each use. Avoid leaving adhesive in nozzles for extended periods of time.
- Keep container sealed when not in use. Care should be taken not to allow product contamination or air entrapment when transferring to, or storing in, other containers.
- Do not mix new and used adhesive in the same container.

**Safety:**

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

*AIM IS ISO9001:2000 CERTIFIED*

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The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. All information pertaining to solder paste is produced with 45-micron powder. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to

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